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Details	
Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I²C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	87
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 24x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08dv128cll

Table 4-2. Direct-Page Register Summary (Sheet 4 of 4)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x0075	PTKDD	PTKDD7	PTKDD6	PTKDD5	PTKDD4	PTKDD3	PTKDD2	PTKDD1	PTKDD0
0x0076	PTLD	PTLD7	PTLD6	PTLD5	PTLD4	PTLD3	PTLD2	PTLD1	PTLD0
0x0077	PTLDD	PTLDD7	PTLDD6	PTLDD5	PTLDD4	PTLDD3	PTLDD2	PTLDD1	PTLDD0
0x0078	PPAGE	0	0	0	0	0	XA16	XA15	XA14
0x0079	LAP2	0	0	0	0	0	0	0	LA16
0x007A	LAP1	LA15	LA14	LA13	LA12	LA11	LA10	LA9	LA8
0x007B	LAP0	LA7	LA6	LA5	LA4	LA3	LA2	LA1	LA0
0x007C	LWP	D7	D6	D5	D4	D3	D2	D1	D0
0x007D	LBP	D7	D6	D5	D4	D3	D2	D1	D0
0x007E	LB	D7	D6	D5	D4	D3	D2	D1	D0
0x007F	LAPAB	D7	D6	D5	D4	D3	D2	D1	D0

High-page registers, shown in Table 4-3, are accessed much less often than other I/O and control registers so they have been located outside the direct addressable memory space, starting at 0x1800.

Table 4-3. High-Page Register Summary (Sheet 1 of 5)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x1800	SRS	POR	PIN	COP	ILOP	ILAD	LOC	LVD	0
0x1801	SBDFR	0	0	0	0	0	0	0	BDFR
0x1802	SOPT1	COPT		STOPE	SCI2PS	IIC1PS	0	0	0
0x1803	SOPT2	COPCLKS	COPW	0	ADHTS	0	MCSEL		
0x1804 – 0x1805	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1806	SDIDH	—	—	—	—	ID11	ID10	ID9	ID8
0x1807	SDIDL	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
0x1808	Reserved	—	—	—	—	—	—	—	—
0x1809	SPMSC1	LVWF	LVWACK	LVWIE	LVDRE	LVDSE	LVDE	0	BGBE
0x180A	SPMSC2	0	0	LVDV	LVWV	PPDF	PPDACK	—	PPDC
0x180B– 0x180F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1810	DBGCAH	Bit 15	14	13	12	11	10	9	Bit 8
0x1811	DBGCAL	Bit 7	6	5	4	3	2	1	Bit 0
0x1812	DBGCBH	Bit 15	14	13	12	11	10	9	Bit 8
0x1813	DBGCBL	Bit 7	6	5	4	3	2	1	Bit 0
0x1814	DBGCCH	Bit 15	14	13	12	11	10	9	Bit 8
0x1815	DBGCCL	Bit 7	6	5	4	3	2	1	Bit 0
0x1816	DBGFH	Bit 15	14	13	12	11	10	9	Bit 8
0x1817	DBGFL	Bit 7	6	5	4	3	2	1	Bit 0
0x1818	DBGCAX	RWAEN	RWA	PAGSEL	0	0	0	0	Bit 16
0x1819	DBGCBX	RWBEN	RWB	PAGSEL	0	0	0	0	Bit 16

Table 4-3. High-Page Register Summary (Sheet 3 of 5)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x1849	PTBSE	PTBSE7	PTBSE6	PTBSE5	PTBSE4	PTBSE3	PTBSE2	PTBSE1	PTBSE0
0x184A	PTBDS	PTBDS7	PTBDS6	PTBDS5	PTBDS4	PTBDS3	PTBDS2	PTBDS1	PTBDS0
0x184B	Reserved	—	—	—	—	—	—	—	—
0x184C	PTBSC	0	0	0	0	PTBIF	PTBACK	PTBIE	PTBMOD
0x184D	PTBPS	PTBPS7	PTBPS6	PTBPS5	PTBPS4	PTBPS3	PTBPS2	PTBPS1	PTBPS0
0x184E	PTBES	PTBES7	PTBES6	PTBES5	PTBES4	PTBES3	PTBES2	PTBES1	PTBES0
0x184F	Reserved	—	—	—	—	—	—	—	—
0x1850	PTCPE	PTCPE7	PTCPE6	PTCPE5	PTCPE4	PTCPE3	PTCPE2	PTCPE1	PTCPE0
0x1851	PTCSE	PTCSE7	PTCSE6	PTCSE5	PTCSE4	PTCSE3	PTCSE2	PTCSE1	PTCSE0
0x1852	PTCDS	PTCDS7	PTCDS6	PTCDS5	PTCDS4	PTCDS3	PTCDS2	PTCDS1	PTCDS0
0x1853– 0x1857	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1858	PTDPE	PTDPE7	PTDPE6	PTDPE5	PTDPE4	PTDPE3	PTDPE2	PTDPE1	PTDPE0
0x1859	PTDSE	PTDSE7	PTDSE6	PTDSE5	PTDSE4	PTDSE3	PTDSE2	PTDSE1	PTDSE0
0x185A	PTDDS	PTDDS7	PTDDS6	PTDDS5	PTDDS4	PTDDS3	PTDDS2	PTDDS1	PTDDS0
0x185B	Reserved	—	—	—	—	—	—	—	—
0x185C	PTDSC	0	0	0	0	PTDIF	PTDACK	PTDIE	PTDMOD
0x185D	PTDPS	PTDPS7	PTDPS6	PTDPS5	PTDPS4	PTDPS3	PTDPS2	PTDPS1	PTDPS0
0x185E	PTDES	PTDES7	PTDES6	PTDES5	PTDES4	PTDES3	PTDES2	PTDES1	PTDES0
0x185F	Reserved	—	—	—	—	—	—	—	—
0x1860	PTEPE	PTEPE7	PTEPE6	PTEPE5	PTEPE4	PTEPE3	PTEPE2	PTEPE1	PTEPE0
0x1861	PTESE	PTESE7	PTESE6	PTESE5	PTESE4	PTESE3	PTESE2	PTESE1	PTESE0
0x1862	PTEDS	PTEDS7	PTEDS6	PTEDS5	PTEDS4	PTEDS3	PTEDS2	PTEDS1	PTEDS0
0x1863– 0x1867	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1868	PTFPE	PTFPE7	PTFPE6	PTFPE5	PTFPE4	PTFPE3	PTFPE2	PTFPE1	PTFPE0
0x1869	PTFSE	PTFSE7	PTFSE6	PTFSE5	PTFSE4	PTFSE3	PTFSE2	PTFSE1	PTFSE0
0x186A	PTFDS	PTFDS7	PTFDS6	PTFDS5	PTFDS4	PTFDS3	PTFDS2	PTFDS1	PTFDS0
0x186B– 0x186F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1870	PTGPE	PTGPE7	PTGPE6	PTGPE5	PTGPE4	PTGPE3	PTGPE2	PTGPE1	PTGPE0
0x1871	PTGSE	PTGSE7	PTGSE6	PTGSE5	PTGSE4	PTGSE3	PTGSE2	PTGSE1	PTGSE0
0x1872	PTGDS	PTGDS7	PTGDS6	PTGDS5	PTGDS4	PTGDS3	PTGDS2	PTGDS1	PTGDS0
0x1873	Reserved	—	—	—	—	—	—	—	—
0x1874	PTHPE	PTHPE7	PTHPE6	PTHPE5	PTHPE4	PTHPE3	PTHPE2	PTHPE1	PTHPE0
0x1875	PTHSE	PTHSE7	PTHSE6	PTHSE5	PTHSE4	PTHSE3	PTHSE2	PTHSE1	PTHSE0
0x1876	PTHDS	PTHDS7	PTHDS6	PTHDS5	PTHDS4	PTHDS3	PTHDS2	PTHDS1	PTHDS0
0x1877	Reserved	—	—	—	—	—	—	—	—
0x1878	PTJPE	PTJPE7	PTJPE6	PTJPE5	PTJPE4	PTJPE3	PTJPE2	PTJPE1	PTJPE0
0x1879	PTJSE	PTJSE7	PTJSE6	PTJSE5	PTJSE4	PTJSE3	PTJSE2	PTJSE1	PTJSE0

6.5.2.5 Port B Drive Strength Selection Register (PTBDS)

	7	6	5	4	3	2	1	0
R/W	PTBDS7	PTBDS6	PTBDS5	PTBDS4	PTBDS3	PTBDS2	PTBDS1	PTBDS0
Reset:	0	0	0	0	0	0	0	0

Figure 6-15. Drive Strength Selection for Port B Register (PTBDS)

Table 6-13. PTBDS Register Field Descriptions

Field	Description
7:0 PTBDS[7:0]	**Output Drive Strength Selection for Port B Bits** — Each of these control bits selects between low and high output drive for the associated PTB pin. For port B pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port B bit n. 1 High output drive strength selected for port B bit n.

6.5.2.6 Port B Interrupt Status and Control Register (PTBSC)

	7	6	5	4	3	2	1	0
R	0	0	0	0	PTBIF	0	PTBIE	PTBMOD
W						PTBACK		
Reset:	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 6-16. Port B Interrupt Status and Control Register (PTBSC)

Table 6-14. PTBSC Register Field Descriptions

Field	Description
3 PTBIF	**Port B Interrupt Flag** — PTBIF indicates when a Port B interrupt is detected. Writes have no effect on PTBIF. 0 No Port B interrupt detected. 1 Port B interrupt detected.
2 PTBACK	**Port B Interrupt Acknowledge** — Writing a 1 to PTBACK is part of the flag clearing mechanism. PTBACK always reads as 0.
1 PTBIE	**Port B Interrupt Enable** — PTBIE determines whether a port B interrupt is requested. 0 Port B interrupt request not enabled. 1 Port B interrupt request enabled.
0 PTBMOD	**Port B Detection Mode** — PTBMOD (along with the PTBES bits) controls the detection mode of the port B interrupt pins. 0 Port B pins detect edges only. 1 Port B pins detect both edges and levels.

6.5.4.7 Port D Interrupt Pin Select Register (PTDPS)

	7	6	5	4	3	2	1	0
R W	PTDPS7	PTDPS6	PTDPS5	PTDPS4	PTDPS3	PTDPS2	PTDPS1	PTDPS0
Reset:	0	0	0	0	0	0	0	0

Figure 6-30. Port D Interrupt Pin Select Register (PTDPS)

Table 6-28. PTDPS Register Field Descriptions

Field	Description
7:0 PTDPS[7:0]	**Port D Interrupt Pin Selects** — Each of the PTDPSn bits enable the corresponding port D interrupt pin. 0 Pin not enabled as interrupt. 1 Pin enabled as interrupt.

6.5.4.8 Port D Interrupt Edge Select Register (PTDES)

	7	6	5	4	3	2	1	0
R W	PTDES7	PTDES6	PTDES5	PTDES4	PTDES3	PTDES2	PTDES1	PTDES0
Reset:	0	0	0	0	0	0	0	0

Figure 6-31. Port D Edge Select Register (PTDES)

Table 6-29. PTDES Register Field Descriptions

Field	Description
7:0 PTDES[7:0]	**Port D Edge Selects** — Each of the PTDESn bits serves a dual purpose by selecting the polarity of the active interrupt edge as well as selecting a pull-up or pull-down device if enabled. 0 A pull-up device is connected to the associated pin and detects falling edge/low level for interrupt generation. 1 A pull-down device is connected to the associated pin and detects rising edge/high level for interrupt generation.

Chapter 7
Central Processor Unit (S08CPUV5)

7.1 Introduction

This section provides summary information about the registers, addressing modes, and instruction set of the CPU of the HCS08 Family. For a more detailed discussion, refer to the *HCS08 Family Reference Manual, volume 1,* Freescale Semiconductor document order number HCS08RMV1/D.

The HCS08 CPU is fully source- and object-code-compatible with the M68HC08 CPU. Several instructions and enhanced addressing modes were added to improve C compiler efficiency and to support a new background debug system which replaces the monitor mode of earlier M68HC08 microcontrollers (MCU).

7.1.1 Features

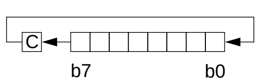
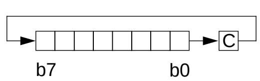
Features of the HCS08 CPU include:

- Object code fully upward-compatible with M68HC05 and M68HC08 Families
- 64-KB CPU address space with banked memory management unit for greater than 64 KB
- 16-bit stack pointer (any size stack anywhere in 64-KB CPU address space)
- 16-bit index register (H:X) with powerful indexed addressing modes
- 8-bit accumulator (A)
- Many instructions treat X as a second general-purpose 8-bit register
- Seven addressing modes:
  - Inherent — Operands in internal registers
  - Relative — 8-bit signed offset to branch destination
  - Immediate — Operand in next object code byte(s)
  - Direct — Operand in memory at 0x0000–0x00FF
  - Extended — Operand anywhere in 64-Kbyte address space
  - Indexed relative to H:X — Five submodes including auto increment
  - Indexed relative to SP — Improves C efficiency dramatically
- Memory-to-memory data move instructions with four address mode combinations
- Overflow, half-carry, negative, zero, and carry condition codes support conditional branching on the results of signed, unsigned, and binary-coded decimal (BCD) operations
- Efficient bit manipulation instructions
- Fast 8-bit by 8-bit multiply and 16-bit by 8-bit divide instructions
- STOP and WAIT instructions to invoke low-power operating modes

Table 7-2. Instruction Set Summary (Sheet 6 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR	
						V 1 1 H	I N Z C

MOV *opr8a*,*opr8a*
MOV *opr8a*,X+
MOV #*opr8i*,*opr8a*
MOV ,X+,*opr8a*
	Move
	$(M)_{destination} \leftarrow (M)_{source}$
	In IX+/DIR and DIR/IX+ Modes,
	H:X ← (H:X) + \$0001
		DIR/DIR
		DIR/IX+
		IMM/DIR
		IX+/DIR
			4E dd dd
			5E dd
			6E ii dd
			7E dd
				5
				5
				4
				5
					rpwpp
					rfwpp
					pwpp
					rfwpp
						0 1 1 –	– ↕ ↕ –

MUL	Unsigned multiply X:A ← (X) × (A)	INH	42	5	ffffp	– 1 1 0	– – – 0
NEG *opr8a* NEGA NEGX NEG *oprx8*,X NEG ,X NEG *oprx8*,SP	Negate (Two's Complement) M ← – (M) = \$00 – (M) A ← – (A) = \$00 – (A) X ← – (X) = \$00 – (X) M ← – (M) = \$00 – (M) M ← – (M) = \$00 – (M) M ← – (M) = \$00 – (M)	DIR INH INH IX1 IX SP1	30 dd 40 50 60 ff 70 9E 60 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕
NOP	No Operation — Uses 1 Bus Cycle	INH	9D	1	p	– 1 1 –	– – – –
NSA	Nibble Swap Accumulator A ← (A[3:0]:A[7:4])	INH	62	1	p	– 1 1 –	– – – –
ORA #*opr8i* ORA *opr8a* ORA *opr16a* ORA *oprx16*,X ORA *oprx8*,X ORA ,X ORA *oprx16*,SP ORA *oprx8*,SP	Inclusive OR Accumulator and Memory A ← (A) | (M)	IMM DIR EXT IX2 IX1 IX SP2 SP1	AA ii BA dd CA hh ll DA ee ff EA ff FA 9E DA ee ff 9E EA ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 –	– ↕ ↕ –
PSHA	Push Accumulator onto Stack Push (A); SP ← (SP) – \$0001	INH	87	2	sp	– 1 1 –	– – – –
PSHH	Push H (Index Register High) onto Stack Push (H); SP ← (SP) – \$0001	INH	8B	2	sp	– 1 1 –	– – – –
PSHX	Push X (Index Register Low) onto Stack Push (X); SP ← (SP) – \$0001	INH	89	2	sp	– 1 1 –	– – – –
PULA	Pull Accumulator from Stack SP ← (SP + \$0001); Pull (A)	INH	86	3	ufp	– 1 1 –	– – – –
PULH	Pull H (Index Register High) from Stack SP ← (SP + \$0001); Pull (H)	INH	8A	3	ufp	– 1 1 –	– – – –
PULX	Pull X (Index Register Low) from Stack SP ← (SP + \$0001); Pull (X)	INH	88	3	ufp	– 1 1 –	– – – –
ROL *opr8a* ROLA ROLX ROL *oprx8*,X ROL ,X ROL *oprx8*,SP	Rotate Left through Carry 	DIR INH INH IX1 IX SP1	39 dd 49 59 69 ff 79 9E 69 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕
ROR *opr8a* RORA RORX ROR *oprx8*,X ROR ,X ROR *oprx8*,SP	Rotate Right through Carry 	DIR INH INH IX1 IX SP1	36 dd 46 56 66 ff 76 9E 66 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕

a) BLPE: If a transition through BLPE mode is desired, first set LP (bit 3) in MCGC2 to 1.

b) BLPE/PBE: MCGC3 = 0x58 (%01011000)

   – PLLS (bit 6) set to 1, selects the PLL. At this time, with an RDIV value of %011, the FLL reference divider of 256 is switched to the PLL reference divider of 8 (see Table 8-3), resulting in a reference frequency of 8 MHz/ 8 = 1 MHz. In BLPE mode,changing the PLLS bit only prepares the MCG for PLL usage in PBE mode

   – DIV32 (bit 4) still set at 1. Because the MCG is in a PLL mode, the DIV32 bit is ignored. Keeping it set at 1 makes transitions back into an FLL external mode easier.

   – VDIV (bits 3-0) set to %1000, or multiply-by-32 because 1 MHz reference * 32= 32MHz. In BLPE mode, the configuration of the VDIV bits does not matter because the PLL is disabled. Changing them only sets up the multiply value for PLL usage in PBE mode

c) BLPE: If transitioning through BLPE mode, clear LP (bit 3) in MCGC2 to 0 here to switch to PBE mode

d) PBE: Loop until PLLST (bit 5) in MCGSC is set, indicating that the current source for the PLLS clock is the PLL

e) PBE: Then loop until LOCK (bit 6) in MCGSC is set, indicating that the PLL has acquired lock

3. Lastly, PBE mode transitions into PEE mode:

   a) MCGC1 = 0x18 (%00011000)

      – CLKS (bits7 and 6) in MCGSC1 set to %00 in order to select the output of the PLL as the system clock source

   b) Loop until CLKST (bits 3 and 2) in MCGSC are %11, indicating that the PLL output is selected to feed MCGOUT in the current clock mode

      – Now, With an RDIV of divide-by-8, a BDIV of divide-by-1, and a VDIV of multiply-by-32, MCGOUT = [(8 MHz / 8) * 32] / 1 = 32 MHz, and the bus frequency is MCGOUT / 2, or 16 MHz

8.5.3.2 Example # 2: Moving from PEE to BLPI Mode: Bus Frequency =16 kHz

In this example, the MCG will move through the proper operational modes from PEE mode with an 8MHz crystal configured for an 16 MHz bus frequency (see previous example) to BLPI mode with a 16 kHz bus frequency.First, the code sequence will be described. Then a flowchart will be included which illustrates the sequence.

1. First, PEE must transition to PBE mode:
   a) MCGC1 = 0x98 (%10011000)
      – CLKS (bits 7 and 6) set to %10 in order to switch the system clock source to the external reference clock
   b) Loop until CLKST (bits 3 and 2) in MCGSC are %10, indicating that the external reference clock is selected to feed MCGOUT
2. Then, PBE must transition either directly to FBE mode or first through BLPE mode and then to FBE mode:
   a) BLPE: If a transition through BLPE mode is desired, first set LP (bit 3) in MCGC2 to 1
   b) BLPE/FBE: MCGC3 = 0x18(%00011000)
      – PLLS (bit 6) clear to 0 to select the FLL. At this time, with an RDIV value of %011, the PLL reference divider of 8 is switched to an FLL divider of 256 (see Table 8-2), resulting in a reference frequency of 8 MHz / 256 = 31.25 kHz. If RDIV was not previously set to %011 (necessary to achieve required 31.25-39.06 kHz FLL reference frequency with an 8 MHz external source frequency), it must be changed prior to clearing the PLLS bit. In BLPE mode,changing this bit only prepares the MCG for FLL usage in FBE mode. With PLLS = 0, the VDIV value does not matter.
      – DIV32 (bit 4) set to 1 (if previously cleared), automatically switches RDIV bits to the proper reference divider for the FLL clock (divide-by-256)
   c) BLPE: If transitioning through BLPE mode, clear LP (bit 3) in MCGC2 to 0 here to switch to FBE mode
   d) FBE: Loop until PLLST (bit 5) in MCGSC is clear, indicating that the current source for the PLLS clock is the FLL
   e) FBE: Optionally, loop until LOCK (bit 6) in the MCGSC is set, indicating that the FLL has acquired lock. Although the FLL is bypassed in FBE mode, it is still enabled and running.
3. Next, FBE mode transitions into FBI mode:
   a) MCGC1 = 0x5C (%01011100)
      – CLKS (bits7 and 6) in MCGSC1 set to %01 in order to switch the system clock to the internal reference clock

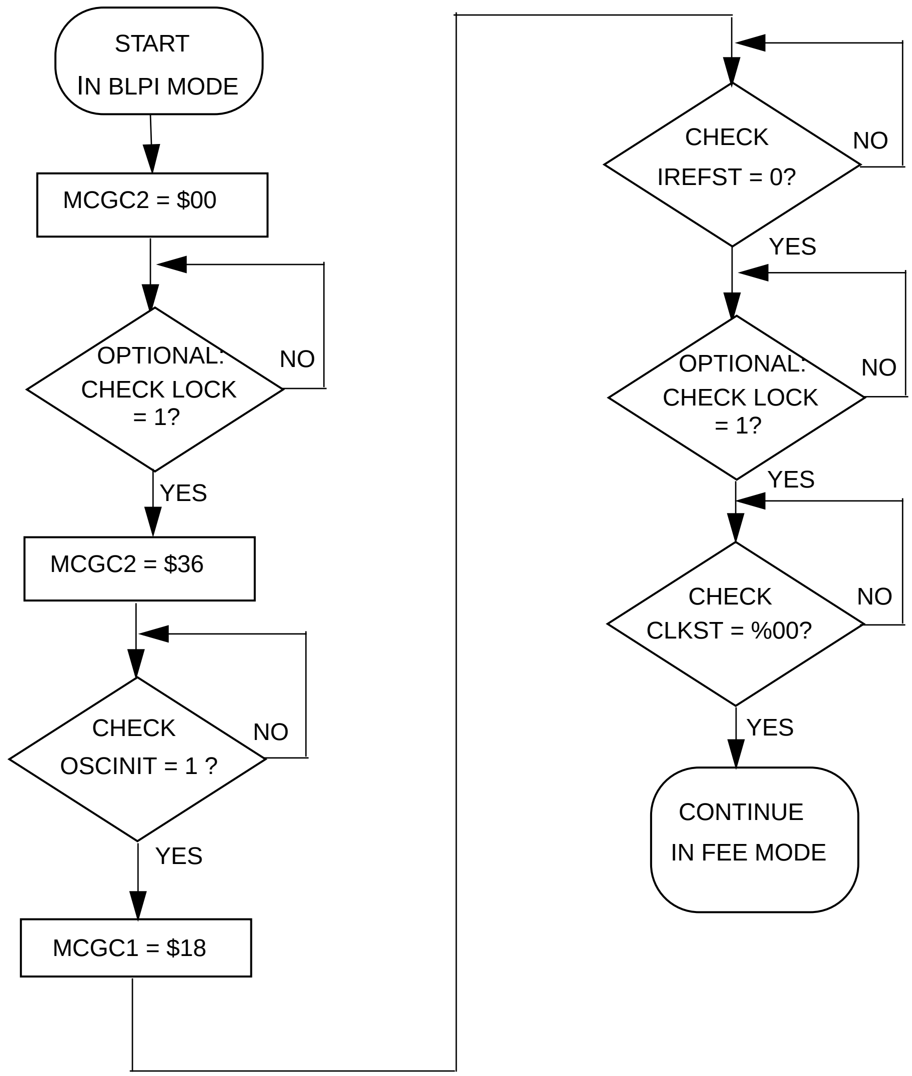


Figure 8-12. Flowchart of BLPI to FEE Mode Transition using an 8 MHz crystal

8.5.4 Calibrating the Internal Reference Clock (IRC)

The IRC is calibrated by writing to the MCGTRM register first, then using the FTRIM bit to “fine tune” the frequency. We will refer to this total 9-bit value as the trim value, ranging from 0x000 to 0x1FF, where the FTRIM bit is the LSB.

The trim value after reset is the factory trim value unless the device resets into any BDM mode in which case it is 0x800. Writing a larger value will decrease the frequency and smaller values will increase the frequency. The trim value is linear with the period, except that slight variations in wafer fab processing produce slight non-linearities between trim value and period. These non-linearities are why an iterative

Table 10-11. APCTL2 Register Field Descriptions

Field	Description
7 ADPC15	ADC Pin Control 15. ADPC15 controls the pin associated with channel AD15. 0 AD15 pin I/O control enabled 1 AD15 pin I/O control disabled
6 ADPC14	ADC Pin Control 14. ADPC14 controls the pin associated with channel AD14. 0 AD14 pin I/O control enabled 1 AD14 pin I/O control disabled
5 ADPC13	ADC Pin Control 13. ADPC13 controls the pin associated with channel AD13. 0 AD13 pin I/O control enabled 1 AD13 pin I/O control disabled
4 ADPC12	ADC Pin Control 12. ADPC12 controls the pin associated with channel AD12. 0 AD12 pin I/O control enabled 1 AD12 pin I/O control disabled
3 ADPC11	ADC Pin Control 11. ADPC11 controls the pin associated with channel AD11. 0 AD11 pin I/O control enabled 1 AD11 pin I/O control disabled
2 ADPC10	ADC Pin Control 10. ADPC10 controls the pin associated with channel AD10. 0 AD10 pin I/O control enabled 1 AD10 pin I/O control disabled
1 ADPC9	ADC Pin Control 9. ADPC9 controls the pin associated with channel AD9. 0 AD9 pin I/O control enabled 1 AD9 pin I/O control disabled
0 ADPC8	ADC Pin Control 8. ADPC8 controls the pin associated with channel AD8. 0 AD8 pin I/O control enabled 1 AD8 pin I/O control disabled

10.3.10 Pin Control 3 Register (APCTL3)

APCTL3 controls channels 16–23 of the ADC module.

	7	6	5	4	3	2	1	0
R W	ADPC23	ADPC22	ADPC21	ADPC20	ADPC19	ADPC18	ADPC17	ADPC16
Reset:	0	0	0	0	0	0	0	0

Figure 10-12. Pin Control 3 Register (APCTL3)

Table 11-9. IICxC2 Field Descriptions

Field	Description
7 GCAEN	**General Call Address Enable.** The GCAEN bit enables or disables general call address. 0 General call address is disabled 1 General call address is enabled
6 ADEXT	**Address Extension.** The ADEXT bit controls the number of bits used for the slave address. 0 7-bit address scheme 1 10-bit address scheme
2–0 AD[10:8]	Slave Address. The AD[10:8] field contains the upper three bits of the slave address in the 10-bit address scheme. This field is only valid when the ADEXT bit is set.

11.4 Functional Description

This section provides a complete functional description of the IIC module.

11.4.1 IIC Protocol

The IIC bus system uses a serial data line (SDA) and a serial clock line (SCL) for data transfer. All devices connected to it must have open drain or open collector outputs. A logic AND function is exercised on both lines with external pull-up resistors. The value of these resistors is system dependent.

Normally, a standard communication is composed of four parts:

- Start signal
- Slave address transmission
- Data transfer
- Stop signal

The stop signal should not be confused with the CPU stop instruction. The IIC bus system communication is described briefly in the following sections and illustrated in Figure 11-9.

Arbitration is lost in the following circumstances:

- SDA sampled as a low when the master drives a high during an address or data transmit cycle.
- SDA sampled as a low when the master drives a high during the acknowledge bit of a data receive cycle.
- A start cycle is attempted when the bus is busy.
- A repeated start cycle is requested in slave mode.
- A stop condition is detected when the master did not request it.

This bit must be cleared by software writing a 1 to it.

12.1.1 Features

The basic features of the MSCAN are as follows:

- Implementation of the CAN protocol — Version 2.0A/B
  - Standard and extended data frames
  - Zero to eight bytes data length
  - Programmable bit rate up to 1 Mbps[1]
  - Support for remote frames
- Five receive buffers with FIFO storage scheme
- Three transmit buffers with internal prioritization using a "local priority" concept
- Flexible maskable identifier filter supports two full-size (32-bit) extended identifier filters, or four 16-bit filters, or eight 8-bit filters
- Programmable wakeup functionality with integrated low-pass filter
- Programmable loopback mode supports self-test operation
- Programmable listen-only mode for monitoring of CAN bus
- Programmable bus-off recovery functionality
- Separate signalling and interrupt capabilities for all CAN receiver and transmitter error states (warning, error passive, bus-off)
- Programmable MSCAN clock source either bus clock or oscillator clock
- Internal timer for time-stamping of received and transmitted messages
- Three low-power modes: sleep, power down, and MSCAN enable
- Global initialization of configuration registers

12.1.2 Modes of Operation

The following modes of operation are specific to the MSCAN. See Section 12.5, "Functional Description," for details.

- Listen-Only Mode
- MSCAN Sleep Mode
- MSCAN Initialization Mode
- MSCAN Power Down Mode
- Loopback Self Test Mode

1. Depending on the actual bit timing and the clock jitter of the PLL.

Table 12-10. CANRIER Register Field Descriptions

Field	Description
7 WUPIE[1]	**Wake-Up Interrupt Enable** 0 No interrupt request is generated from this event. 1 A wake-up event causes a Wake-Up interrupt request.
6 CSCIE	**CAN Status Change Interrupt Enable** 0 No interrupt request is generated from this event. 1 A CAN Status Change event causes an error interrupt request.
5:4 RSTATE[1:0]	**Receiver Status Change Enable** — These RSTAT enable bits control the sensitivity level in which receiver state changes are causing CSCIF interrupts. Independent of the chosen sensitivity level the RSTAT flags continue to indicate the actual receiver state and are only updated if no CSCIF interrupt is pending. 00 Do not generate any CSCIF interrupt caused by receiver state changes. 01 Generate CSCIF interrupt only if the receiver enters or leaves "bus-off" state. Discard other receiver state changes for generating CSCIF interrupt. 10 Generate CSCIF interrupt only if the receiver enters or leaves "RxErr" or "bus-off"[2] state. Discard other receiver state changes for generating CSCIF interrupt. 11 Generate CSCIF interrupt on all state changes.
3:2 TSTATE[1:0]	**Transmitter Status Change Enable** — These TSTAT enable bits control the sensitivity level in which transmitter state changes are causing CSCIF interrupts. Independent of the chosen sensitivity level, the TSTAT flags continue to indicate the actual transmitter state and are only updated if no CSCIF interrupt is pending. 00 Do not generate any CSCIF interrupt caused by transmitter state changes. 01 Generate CSCIF interrupt only if the transmitter enters or leaves "bus-off" state. Discard other transmitter state changes for generating CSCIF interrupt. 10 Generate CSCIF interrupt only if the transmitter enters or leaves "TxErr" or "bus-off" state. Discard other transmitter state changes for generating CSCIF interrupt. 11 Generate CSCIF interrupt on all state changes.
1 OVRIE	**Overrun Interrupt Enable** 0 No interrupt request is generated from this event. 1 An overrun event causes an error interrupt request.
0 RXFIE	**Receiver Full Interrupt Enable** 0 No interrupt request is generated from this event. 1 A receive buffer full (successful message reception) event causes a receiver interrupt request.

[1] WUPIE and WUPE (see Section 12.3.1, "MSCAN Control Register 0 (CANCTL0)") must both be enabled if the recovery mechanism from stop or wait is required.

[2] Bus-off state is defined by the CAN standard (see Bosch CAN 2.0A/B protocol specification: for only transmitters. Because the only possible state change for the transmitter from bus-off to TxOK also forces the receiver to skip its current state to RxOK, the coding of the RXSTAT[1:0] flags define an additional bus-off state for the receiver (see Section 12.3.4.1, "MSCAN Receiver Flag Register (CANRFLG)").

12.3.6 MSCAN Transmitter Flag Register (CANTFLG)

The transmit buffer empty flags each have an associated interrupt enable bit in the CANTIER register.

12.5.3.2 Protocol Violation Protection

The MSCAN protects the user from accidentally violating the CAN protocol through programming errors. The protection logic implements the following features:

- The receive and transmit error counters cannot be written or otherwise manipulated.
- All registers which control the configuration of the MSCAN cannot be modified while the MSCAN is on-line. The MSCAN has to be in Initialization Mode. The corresponding INITRQ/INITAK handshake bits in the CANCTL0/CANCTL1 registers (see Section 12.3.1, "MSCAN Control Register 0 (CANCTL0)") serve as a lock to protect the following registers:
  — MSCAN control 1 register (CANCTL1)
  — MSCAN bus timing registers 0 and 1 (CANBTR0, CANBTR1)
  — MSCAN identifier acceptance control register (CANIDAC)
  — MSCAN identifier acceptance registers (CANIDAR0–CANIDAR7)
  — MSCAN identifier mask registers (CANIDMR0–CANIDMR7)
- The TXCAN pin is immediately forced to a recessive state when the MSCAN goes into the power down mode or initialization mode (see Section 12.5.5.6, "MSCAN Power Down Mode," and Section 12.5.5.5, "MSCAN Initialization Mode").
- The MSCAN enable bit (CANE) is writable only once in normal system operation modes, which provides further protection against inadvertently disabling the MSCAN.

12.5.3.3 Clock System

Figure 12-42 shows the structure of the MSCAN clock generation circuitry.

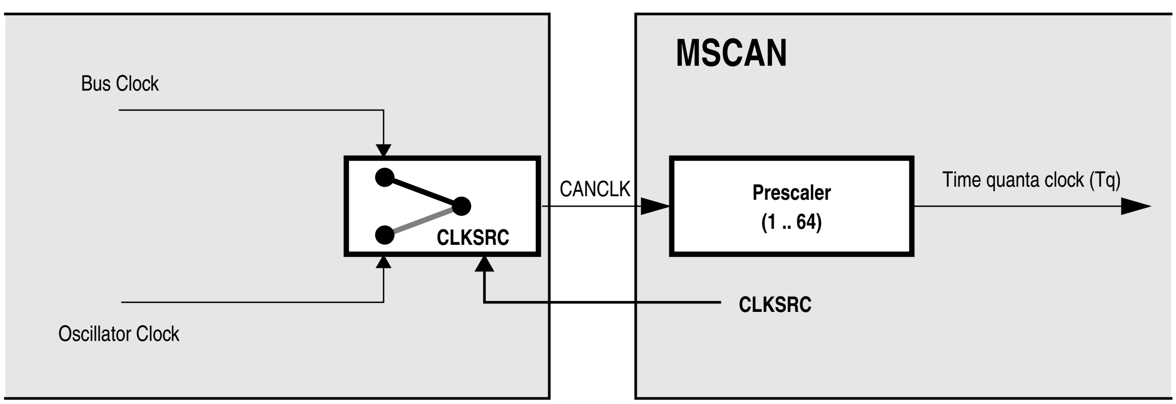


Figure 12-42. MSCAN Clocking Scheme

The clock source bit (CLKSRC) in the CANCTL1 register (12.3.2/-260) defines whether the internal CANCLK is connected to the output of a crystal oscillator (oscillator clock) or to the bus clock.

The clock source has to be chosen such that the tight oscillator tolerance requirements (up to 0.4%) of the CAN protocol are met. Additionally, for high CAN bus rates (1 Mbps), a 45% to 55% duty cycle of the clock is required.

maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for instance, either V_{SS} or V_{DD}).

Table A-2. Absolute Maximum Ratings

Num	Rating	Symbol	Value	Unit
1	Supply voltage	V_{DD}	–0.3 to + 5.8	V
2	Input voltage	V_{In}	– 0.3 to V_{DD} + 0.3	V
3	Instantaneous maximum current Single pin limit (applies to all port pins)[1, 2, 3]	I_D	± 25	mA
4	Maximum current into V_{DD}	I_{DD}	120	mA
5	Storage temperature	T_{stg}	–55 to +150	°C

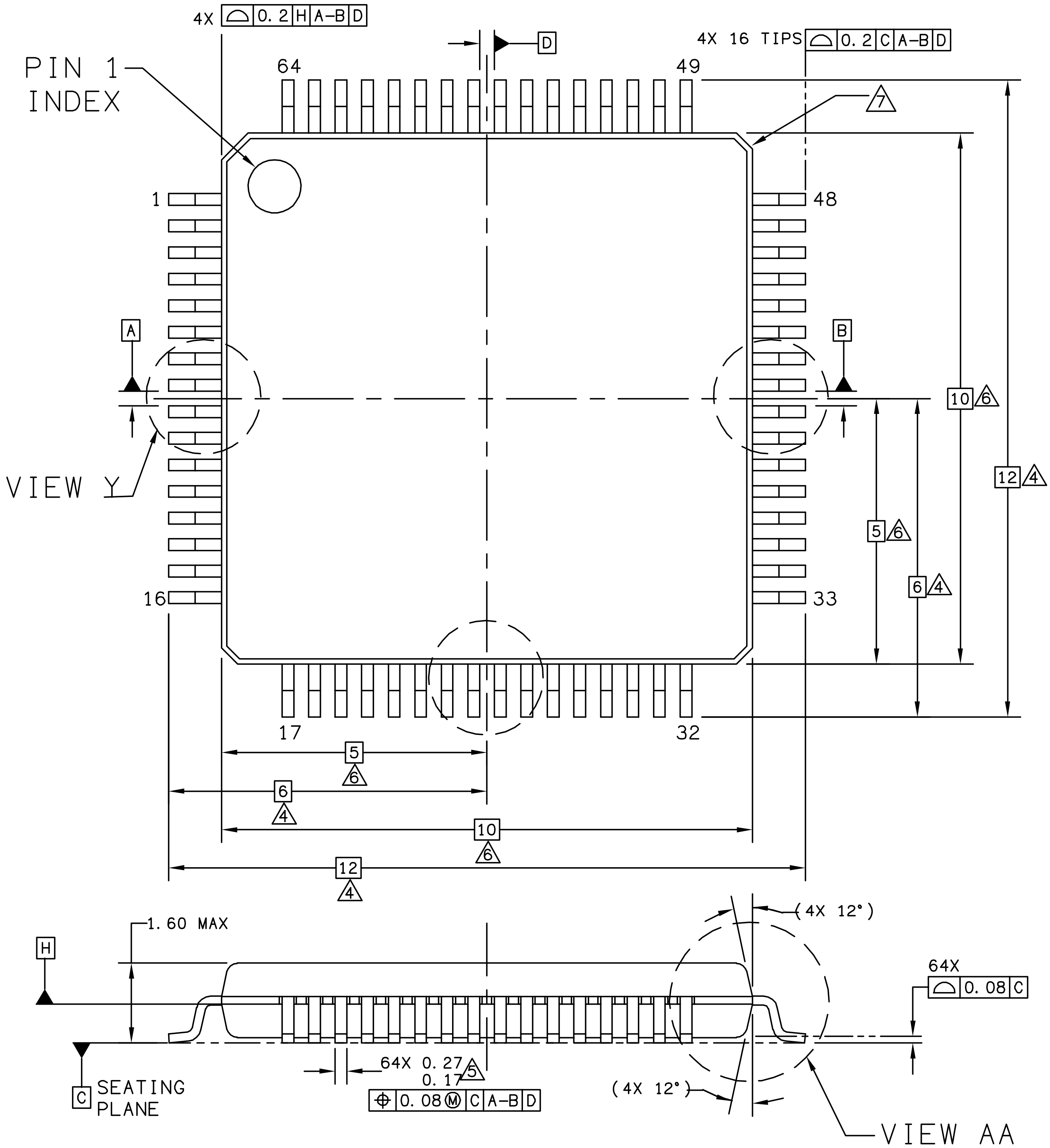
[1] Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive (V_{DD}) and negative (V_{SS}) clamp voltages, then use the larger of the two resistance values.

[2] All functional non-supply pins are internally clamped to V_{SS} and V_{DD}.

[3] Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current ($V_{In} > V_{DD}$) is greater than I_{DD}, the injection current may flow out of V_{DD} and could result in external power supply going out of regulation. Ensure external V_{DD} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if the clock rate is very low which would reduce overall power consumption.

A.4 Thermal Characteristics

This section provides information about operating temperature range, power dissipation, and package thermal resistance. Power dissipation on I/O pins is usually small compared to the power dissipation in on-chip logic and it is user-determined rather than being controlled by the MCU design. In order to take $P_{I/O}$ into account in power calculations, determine the difference between actual pin voltage and V_{SS} or V_{DD} and multiply by the pin current for each I/O pin. Except in cases of unusually high pin current (heavy loads), the difference between pin voltage and V_{SS} or V_{DD} will be very small.



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